



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® 8 x 8 (HVM)					
STRESS	SAMPLE SIZE	DEVICE HRS./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	80	40 000	200 °C + N2	0	0.00
HAST	656	65 600	130 °C, 85 % RH	0	0.00
Pressure Pot	1000	96 000	121 °C, 15 PSIG	0	0.00
Solderability	30	240	883 M2003	0	0.00
Temp. Cycle	1589	1 040 500	-55 °C to 150 °C	0	0.00